

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination FILIPPI ET AL.	
		10/687,475	Examiner	Art Unit Helen Rossoshek
			2825	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Bagnoli et al., Fast analytical thermal modeling of electronic devices and circuits with multi-layer stack mountings", 10-12 Dec. 2003, Electronics Packaging Technology, 2003 5th Conference (EPTC 2003), Page(s):501 - 506
	V	
	W	
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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